

**ABSTRACT OF THE DISCLOSURE**

An inductive device (105) is formed above a substrate (225) having a conductive coil formed around a core (109). The coil comprises segments formed from a first plurality of bond wires (113) and a second plurality of bond wires (111). The first plurality of bond wires  
5 (113) extends between the core (109) and the substrate (225). Each of the first plurality of bond wires is coupled to two of a plurality of wire bond pads (117, 116). The second plurality of bond wires (111) extends over the core (109) and is coupled between two of the plurality of wire bond pads (117, 119). A shield (141) includes a portion that is positioned between the core (109) and the substrate (225).